Title (en)

INTEGRATED CIRCUIT WITH SEVERAL COMPONENTS AND METHOD FOR THE PRODUCTION THEREOF

Title (de)

INTEGRIERTE SCHALTUNGSANORDNUNG MIT MEHREREN BAUELEMENTEN UND VERFAHREN ZU DEREN HERSTELLUNG

Title (fr)

CIRCUIT INTEGRE A PLUSIEURS COMPOSANTS ET SON PROCEDE DE PRODUCTION

Publication

EP 0976156 A1 20000202 (DE)

Application

EP 98925394 A 19980313

Priority

- DE 9800769 W 19980313
- DE 19716102 A 19970417

Abstract (en)

[origin: DE19716102A1] The invention relates to an integrated circuit containing several components, at least one of which is coated by a metallic shielding structure. This component is thus protected from interfering incoupled impulses from its surroundings. The circuit components can, in particular, be fitted next to or on top of each other. In order to produce the metallic shielding structure of a circuit component, at least one indent is produced, which surrounds the component, and which is then lined with metal. The contacts and electric connections of the component are electrically insulated by the metal of the shielding structure. In order to combine two components inside a three-dimensional circuit, the surfaces of the component that face each other can be coated with two different metals, the alloy of which has a melting temperature Ts above the melting temperature T1 of at least one of the metals, as a result of which heating to a temperature between the two melting temperatures leads to a firm assembly.

IPC 1-7

H01L 23/60; H01L 27/06

IPC 8 full level

H01L 21/762 (2006.01); **H01L 23/552** (2006.01); **H01L 23/60** (2006.01); **H01L 27/00** (2006.01)

CPC (source: EP KR US)

H01L 21/76264 (2013.01 - EP US); **H01L 23/552** (2013.01 - EP US); **H01L 23/60** (2013.01 - EP KR US); H01L 21/76289 (2013.01 - EP US); H01L 2224/16145 (2013.01 - EP US); H01L 2924/1301 (2013.01 - EP US); H01L 2924/1305 (2013.01 - EP US)

Citation (search report)

See references of WO 9848459A1

Designated contracting state (EPC)

CH DE FR GB IE IT LI

DOCDB simple family (publication)

DE 19716102 A1 19981022; **DE 19716102 C2 20030925**; EP 0976156 A1 20000202; JP 2001517376 A 20011002; JP 3786429 B2 20060614; KR 100433870 B1 20040604; KR 20010006415 A 20010126; TW 405218 B 20000911; US 6597053 B1 20030722; WO 9848459 A1 19981029

DOCDB simple family (application)

DE 19716102 A 19970417; DE 9800769 W 19980313; EP 98925394 A 19980313; JP 54467198 A 19980313; KR 19997009503 A 19991015; TW 87104008 A 19980318; US 40315799 A 19991015